

# GSC8107E

P-CHANNEL ENHANCEMENT MODE POWER MOSFET

BVDSS	-30V
RDS(ON)	7.0mΩ
ID	-13A

## Description

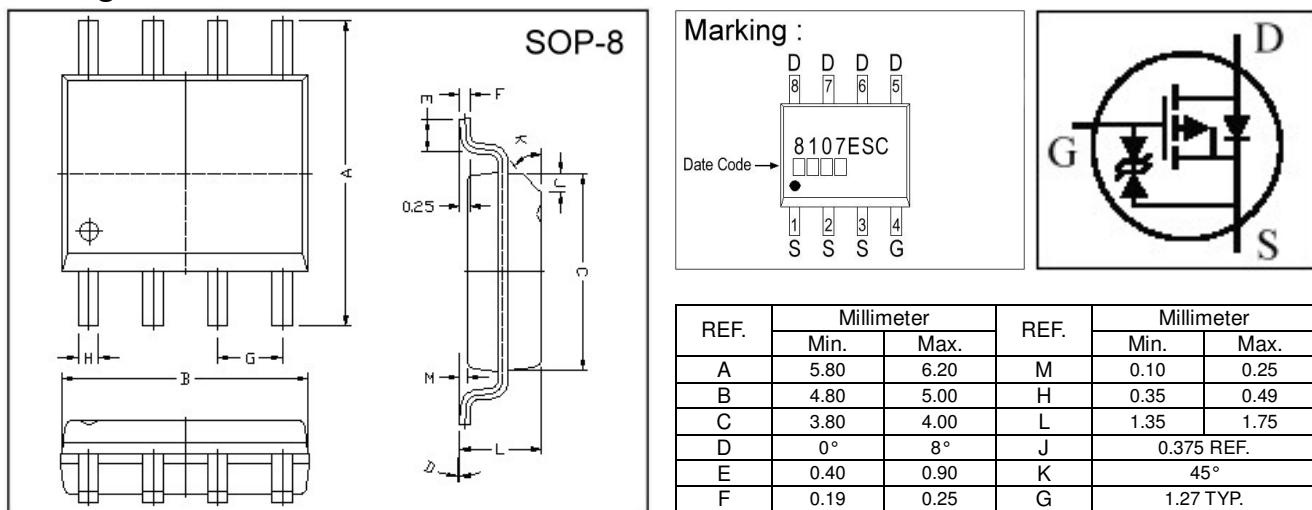
The GSC8107E provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The SOP-8 package is universally preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

## Features

- \*Simple Drive Requirement
- \*Lower On-resistance
- \*Fast Switching Characteristic

## Package Dimensions



## Absolute Maximum Ratings

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	-30	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current <sup>3</sup>	I <sub>D</sub> @TA=25°C	-13	A
Continuous Drain Current <sup>3</sup>	I <sub>D</sub> @TA=70°C	-10	A
Pulsed Drain Current <sup>1</sup>	I <sub>DM</sub>	-52	A
Total Power Dissipation	P <sub>D</sub> @TA=25°C	2.5	W
Linear Derating Factor		0.02	W/°C
Operating Junction and Storage Temperature Range	T <sub>j</sub> , T <sub>stg</sub>	-55 ~ +150	°C

## Thermal Data

Parameter	Symbol	Value	Unit
Thermal Resistance Junction-ambient <sup>3</sup> Max.	R <sub>thj-amb</sub>	50	°C/W

## Electrical Characteristics ( $T_j = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	-30	-	-	V	$\text{V}_{\text{GS}}=0, \text{I}_D=-10\text{mA}$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	-0.8	-	-2.0	V	$\text{V}_{\text{DS}}=10, \text{I}_D=-1\text{mA}$
Forward Transconductance	$\text{g}_{\text{fs}}$	-	31	-	S	$\text{V}_{\text{DS}}=-10\text{V}, \text{I}_D=-6.5\text{A}$
Gate-Source Leakage Current	$\text{I}_{\text{GSS}}$	-	-	$\pm 10$	$\mu\text{A}$	$\text{V}_{\text{GS}}= \pm 16\text{V}$
Drain-Source Leakage Current	$\text{I}_{\text{DSS}}$	-	-	-10	$\mu\text{A}$	$\text{V}_{\text{DS}}=-30\text{V}, \text{V}_{\text{GS}}=0$
Static Drain-Source On-Resistance <sup>2</sup>	$\text{R}_{\text{DS}(\text{ON})}$	-	-	7	$\text{m}\Omega$	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-6.5\text{A}$
		-	-	15		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-6.5\text{A}$
Total Gate Charge <sup>2</sup>	$\text{Q}_{\text{g}}$	-	130	-	$\text{nC}$	$\text{I}_D=-13\text{A}$ $\text{V}_{\text{DS}}=-24\text{V}$ $\text{V}_{\text{GS}}=-10\text{V}$
Gate-Source Charge	$\text{Q}_{\text{gs}}$	-	10	-		
Gate-Drain ("Miller") Change	$\text{Q}_{\text{gd}}$	-	30	-		
Turn-on Delay Time <sup>2</sup>	$\text{T}_{\text{d}(\text{on})}$	-	22	-	$\text{ns}$	$\text{V}_{\text{DS}}=-15\text{V}$ $\text{I}_D=-6.5\text{A}$ $\text{V}_{\text{GS}}=-10\text{V}$ $\text{R}_G=4.7\Omega$ $\text{R}_L=2.3\Omega$
Rise Time	$\text{T}_{\text{r}}$	-	11	-		
Turn-off Delay Time	$\text{T}_{\text{d}(\text{off})}$	-	395	-		
Fall Time	$\text{T}_{\text{f}}$	-	110	-		
Input Capacitance	$\text{C}_{\text{iss}}$	-	5880	-	$\text{pF}$	$\text{V}_{\text{GS}}=0\text{V}$ $\text{V}_{\text{DS}}=-10\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	$\text{C}_{\text{oss}}$	-	1000	-		
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$	-	1050	-		

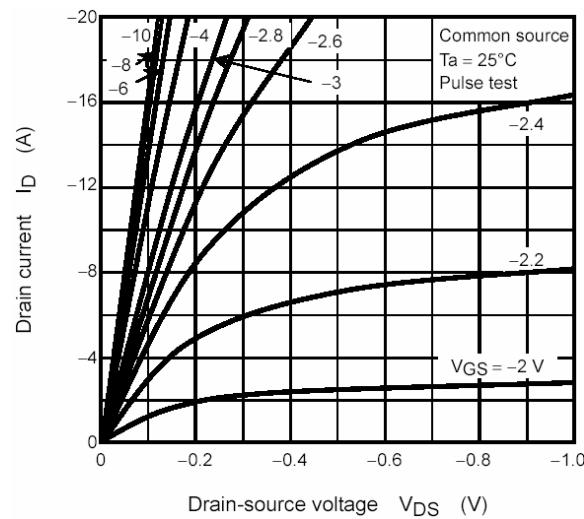
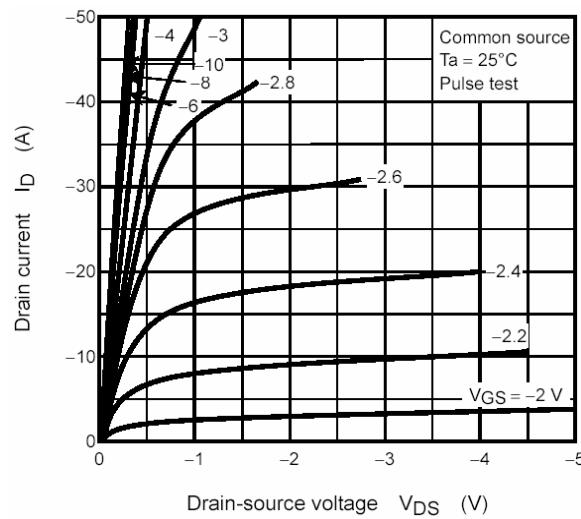
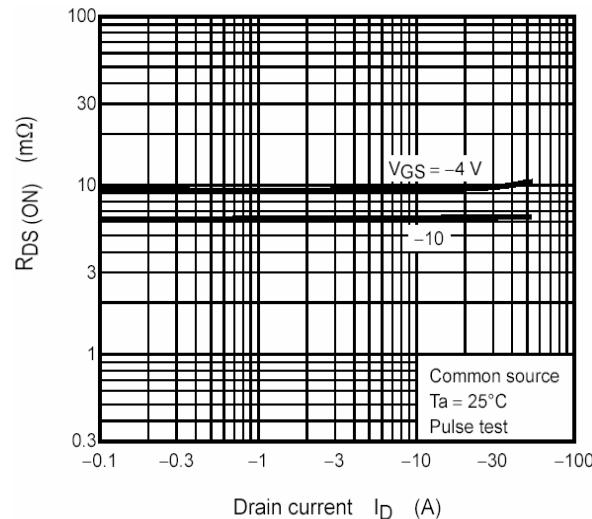
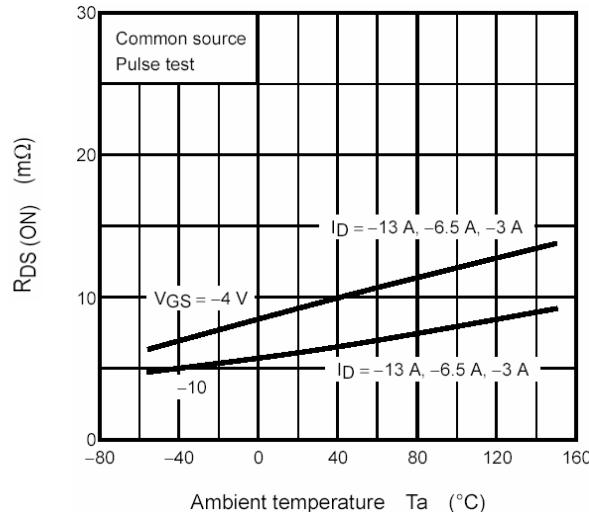
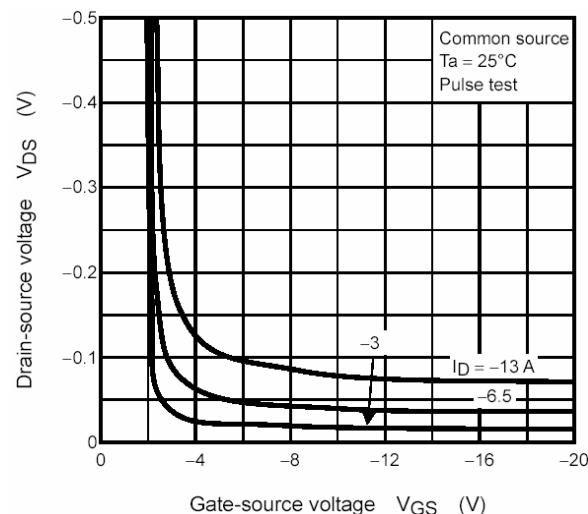
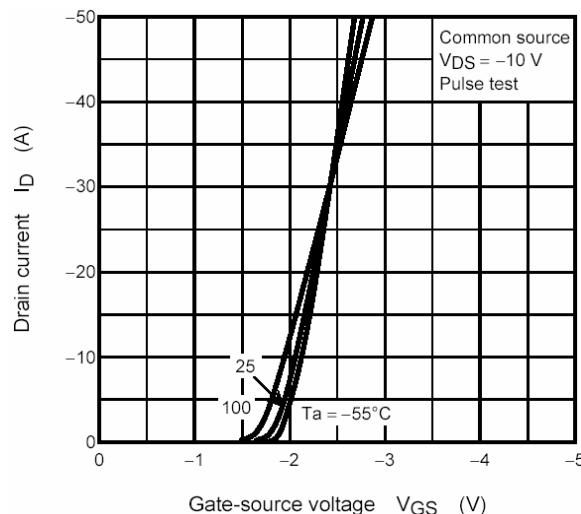
## Source-Drain Diode

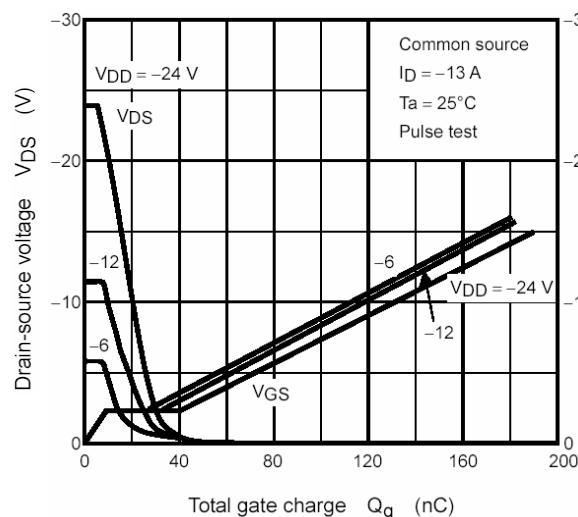
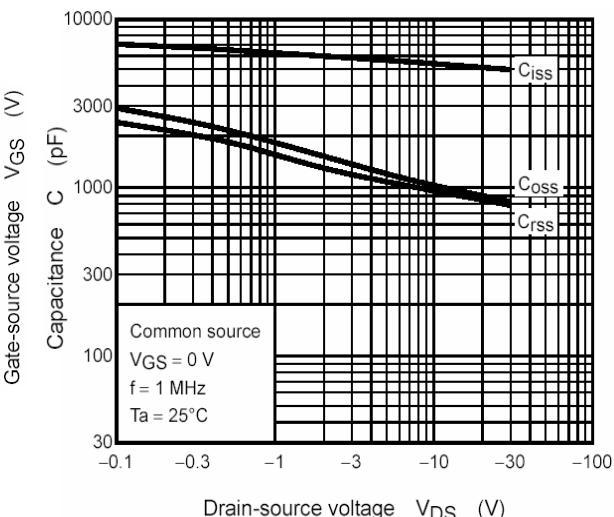
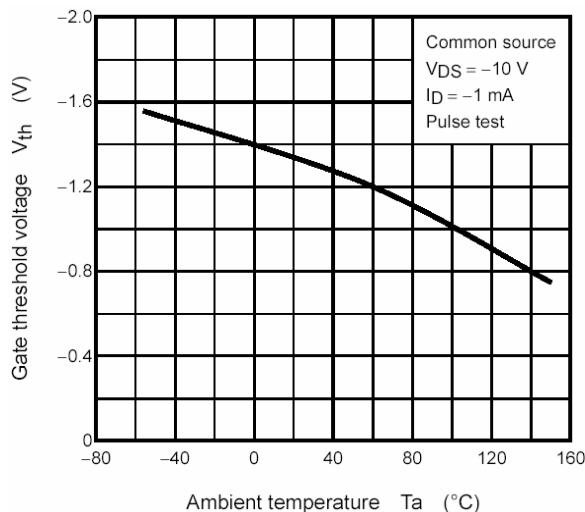
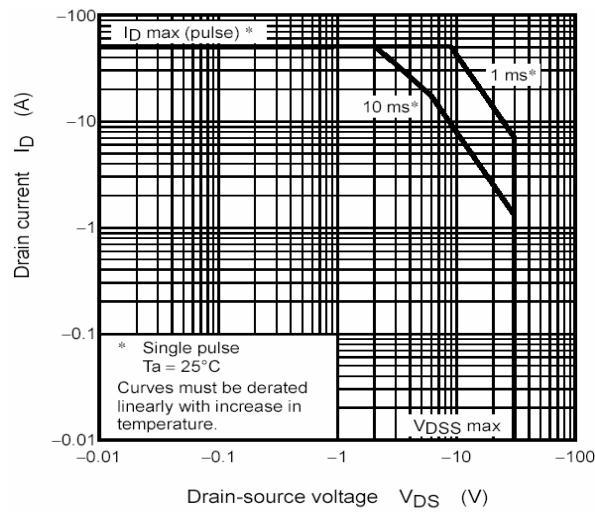
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage <sup>2</sup>	$\text{V}_{\text{SD}}$	-	-	-1.2	V	$\text{I}_S=-13\text{A}, \text{V}_{\text{GS}}=0\text{V}$

Notes: 1. Pulse width limited by Max. junction temperature.

2. Pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .

3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board; 125°C/W when mounted on Min. copper pad.

**Characteristics Curve****Fig 1. Typical Output Characteristics****Fig 2. Typical Output Characteristics****Fig 3. On-Resistance v.s. Drain Current****Fig 4. On-Resistance v.s. Ambient Temperature****Fig 5. Drain-Source Voltage v.s. Gate-Source Voltage****Fig 6. Drain Current v.s. Gate-Source Voltage**

**Fig 7. Gate Charge Characteristics****Fig 8. Typical Capacitance Characteristics****Fig 9. Threshold Voltage****Fig 10. Safe Operating Area****Important Notice:**

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